

Photocouplers Optically Isolation Amplifiers

TLP7820

1. Applications

- · Motor phase and rail current sensing
- · Power inverter current and voltage sensing

2. General

The TLP7820 of isolation amplifiers is designed for current sensing in electronic motor drives. In a typical implementation, motor currents flow through an external resistor and the resulting analog voltage drop is sensed by the TLP7820.

3. Features

- (1) Gain accuracy: ±0.5 % (Gain rank B)
- (2) Gain drift: 0.00012 V/V/°C (typ.)
- (3) Nonlinearity ($V_{IN} = \pm 200 \text{ mV}$): 0.02 % (typ.)
- (4) Input offset voltage: 0.9 mV (typ.)
- (5) V_{OUT} bandwidth (-3 dB): 230 kHz (typ.)
- (6) Operating temperature range: -40 to 105 °C
- (7) Common-mode transient immunity: 15 kV/μs (min)
- (8) Safety standards

UL-approved: UL1577, File No.E67349

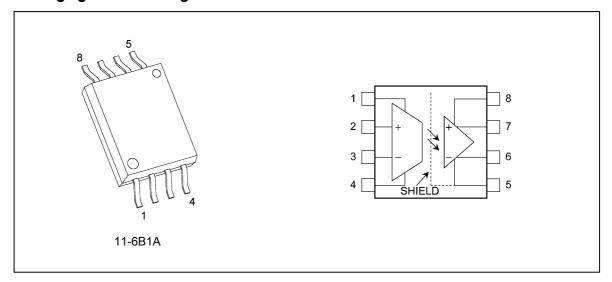
cUL-approved: CSA Component Acceptance Service No.5A File No.E67349 VDE-approved: EN60747-5-5, EN60065, EN60950-1, EN 62368-1 (Note 1)

CQC-approved: GB4943.1, GB8898 Japan Factory

Note 1: When a VDE approved type is needed, please designate the Option (D4).



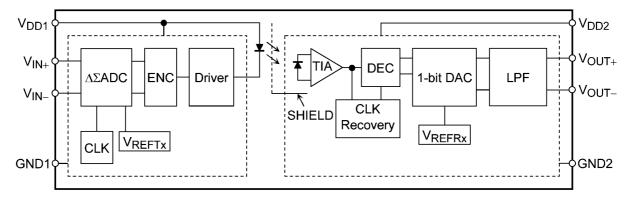
4. Packaging and Pin Assignment



4.1. Pin Assignment

| Pin No. | Symbol | Description |
|---------|-------------------|----------------------------|
| 1 | V_{DD1} | Input side supply voltage |
| 2 | V _{IN+} | Positive input |
| 3 | V _{IN-} | Negative input |
| 4 | GND1 | Input side ground |
| 5 | GND2 | Output side ground |
| 6 | V _{OUT-} | Negative output |
| 7 | V _{OUT+} | Positive output |
| 8 | V_{DD2} | Output side supply voltage |

5. Internal Circuit (Note)



Note: A 0.1- μ F bypass capacitor must be connected between 1 and 4 pins and between 5 and 8 pins.

6. Principle of Operation

6.1. Mechanical Parameters

| Characteristics | Size | Unit |
|------------------------------|-----------|------|
| Height | 2.3 (max) | mm |
| Creepage distances | 8.0 (min) | |
| Clearance | 8.0 (min) | |
| Internal isolation thickness | 0.4 (min) | |

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7. Absolute Maximum Ratings (Note) (Unless otherwise specified, Ta = 25 °C)

| Characteristics | | Symbol | Note | Rating | Unit |
|-------------------------------------|-----------------------------|---------------------------------------|----------|--------------------------------|-------|
| Supply Voltages | | V_{DD1}, V_{DD2} | | -0.5 to 6 | V |
| Steady-state input voltages | | V_{IN+}, V_{IN-} | | -0.5 to V _{DD1} + 0.5 | V |
| Two-second transient input voltages | | V_{IN+}, V_{IN-} | | -6 to V _{DD1} + 0.5 | V |
| Input power dissipation | | P _D | | 72 | mW |
| Input power dissipation derating | (T _a ≥ 110.6 °C) | $\Delta P_D/\Delta T_a$ | | -5.0 | mW/°C |
| Output voltages | | V _{OUT+} , V _{OUT-} | | -0.5 to V _{DD2} + 0.5 | V |
| Output power dissipation | | Po | | 60 | mW |
| Output power dissipation derating | (T _a ≥ 113.0 °C) | $\Delta P_{O}/\Delta T_{a}$ | | -5.0 | mW/°C |
| Operating temperature | | T _{opr} | | -40 to 105 | °C |
| Storage temperature | | T _{stg} | | -55 to 125 | °C |
| Lead soldering temperature | (10 s) | T _{sol} | (Note 1) | 260 | °C |
| Isolation voltage | (AC, 60 s, R.H. ≤ 60 %) | BV _S | (Note 2) | 5000 | Vrms |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note: Ceramic capacitors $(0.1 \,\mu\text{F})$ should be connected between 1 and 4 pins and between 5 and 8 pins to stabilize the operation. Otherwise, this photocoupler may not switch properly. The bypass capacitors should be placed as close as possible to each pin.

Note 1: \geq 2 mm below seating plane.

Note 2: This device is considered as a two-terminal device: Pins 1, 2, 3 and 4 are shorted together, and pins 5, 6, 7 and 8 are shorted together.

8. Recommended Operating Conditions (Note)

| Characteristics | Symbol | Note | Min | Тур. | Max | Unit |
|----------------------------|--------------------|--------------------|------|------|-----|------|
| Input side supply voltage | V _{DD1} | | 4.5 | 5 | 5.5 | V |
| Output side supply voltage | V_{DD2} | | 3 | | 5.5 | |
| Analog input voltage | V_{IN+}, V_{IN-} | (Note 1), (Note 2) | -200 | _ | 200 | mV |
| Ambient temperature | T _a | | -40 | | 105 | °C |

Note: The recommended operating conditions are given as a design guide necessary to obtain the intended performance of the device. Each parameter is an independent value. When creating a system design using this device, the electrical characteristics specified in this data sheet should also be considered.

Note 1: Full-Scale Differential Voltage Input Range(FSR) = ± 300 mV (typ.)

Note 2: When either V_{IN+} or V_{IN-} or both are equal to or greater than V_{DD1} - 2 V (e.g., if V_{DD1} = 5 V, when V_{IN+} and/or V_{IN-} are equal to or greater than 5 V - 2 V = 3 V), isolation amplifiers go into one of the test modes. Do not raise either V_{IN+} or V_{IN-} above this voltage to keep the device in functional mode.



9. Electrical Characteristics

9.1. DC Characteristics (Unless otherwise specified, T_a = -40 to 105 °C, V_{DD1} = 4.5 to 5.5 V, V_{DD2} = 3 to 5.5 V, V_{IN+} = -200 to 200 mV, V_{IN-} = 0 V)

| Characteristics | Symbol | Note | Test Condition | Min | Тур. | Max | Unit |
|--|-------------------------------------|----------|--|------|---------|------|--------|
| Input offset voltage | Vos | | T _a = 25 °C | -0.6 | 0.9 | 2.4 | mV |
| Input offset voltage drift vs ambient temperature | dV _{OS} /dT _a | | | | 2 | 6 | μV/°C |
| Input offset voltage drift vs input side supply voltage | $ dV_{OS}/dV_{DD1} $ | | | l | 120 | l | μV/V |
| Gain (Rank B) | G_0 | (Note 1) | T _a = 25 °C | 8.16 | 8.2 | 8.24 | V/V |
| Gain (Rank A) | G ₁ | (Note 1) | T _a = 25 °C | 8.12 | 8.2 | 8.28 | |
| Gain (None) | G ₃ | (Note 1) | T _a = 25 °C | 7.95 | 8.2 | 8.44 | |
| Gain drift vs ambient temperature | dG/dT _a | | | _ | 0.00012 | _ | V/V/°C |
| V _{OUT} non-linearity (±200 mV) | NL ₂₀₀ | (Note 2) | V _{IN+} = -200 to 200 mV, T _a = 25 °C | _ | 0.02 | 0.13 | % |
| V _{OUT} non-linearity (±200 mV) drift vs ambient temperature | dNL ₂₀₀ /dT _a | | | _ | 0.00007 | _ | %/°C |
| V _{OUT} non-linearity (±100 mV) | NL ₁₀₀ | (Note 2) | V _{IN+} = -100 to 100 mV, T _a = 25 °C | _ | 0.015 | 0.06 | % |
| High-level output voltage | V _{OH} | | V _{IN+} = 400 mV, T _a = 25 °C | _ | 2.497 | _ | V |
| Low-level output voltage | V _{OL} | | V _{IN+} = -400 mV, T _a = 25 °C | _ | 0.0009 | _ | V |
| Input common-mode rejection ratio | CMRR _{IN} | | | _ | 80 | _ | dB |
| Equivalent input resistance | R _{IN} | | | _ | 80 | _ | kΩ |
| Input bias current | I _{IN+} | | V _{IN+} = 0 V, T _a = 25 °C | -1 | -0.055 | | μА |
| Input side supply current (V _{DD1}) | I _{DD1} | | V _{IN+} = 0 V | 1 | 8.6 | 12 | mA |
| Output side supply current (V _{DD2}) | I _{DD2} | | V _{IN+} = 0 V | | 6.2 | 10 | mA |
| V _{OUT} output resistance | R _{OUT} | | V _{OUT+} or V _{OUT-} | _ | 21 | _ | Ω |

Note 1: See section 9.1.1. for gain rank values.

Note 2: The slope of the optimum line is derived by the method of least squares between differential input voltage $(V_{IN+} - V_{IN-})$ and differential output voltage $(V_{OUT+} - V_{OUT-})$. Nonlinearity is defined as a fraction of the half of the peak-to-peak value of differential output voltage deviation divided by the full-scale differential output voltage (OVR).

9.1.1. Gain Rank (Note) (Unless otherwise specified, T_a = 25 °C)

| Rank | Gain Rank Marking | (Min) | Gain (Typ.) | (Max) | Unit |
|-----------------|-------------------|-------|----------------|-------|------|
| None (±3 %) | Blank, A, B | 7.95 | 8.2 | 8.44 | V/V |
| Rank A (±1 %) | A, B | 8.12 | 8.2 | 8.28 | |
| Rank B (±0.5 %) | В | 8.16 | 8.2 | 8.24 | |

Note: The gain is defined as the slope of the optimum line derived by the method of least squares between differential input voltage (V_{IN+} - V_{IN-}) and differential output voltage (V_{OUT+} - V_{OUT-}) in the recommended voltage range.

Note: Specify both the part number and a rank in this format when ordering. Example: Rank B: TLP7820(B



10. AC Characteristics (Note) (Unless otherwise specified, T_a = -40 to 105 °C, V_{DD1} = 4.5 to 5.5 V, V_{DD2} = 3 to 5.5 V)

| Characteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|--|-------------------|--|-----|------|-----|-------|
| V _{OUT} bandwidth (-3 dB) | f _{-3dB} | V_{IN+} = 400 m V_{p-p} , sine wave | 140 | 230 | _ | kHz |
| V _{IN} to V _{OUT} propagation delay time (10 %-10 %) | t _{pD10} | $V_{\text{IN+}}$ = 0 to 200 mV/ μ s step C_L = 15 pF | _ | 1.9 | 2.3 | μS |
| V_{IN} to V_{OUT} propagation delay time (50 %-50 %) | t _{pD50} | | _ | 2.3 | 2.6 | |
| V_{IN} to V_{OUT} propagation delay time (90 %-90 %) | t _{pD90} | | _ | 2.8 | 3.3 | |
| V _{OUT} rise time | t _r | | _ | 1.7 | _ | |
| V _{OUT} fall time | t _f | | _ | 1.7 | _ | |
| Common-mode transient immunity | CMTI | V _{CM} = 1 kV, T _a = 25 °C | 15 | 20 | _ | kV/μs |

Note: All typical values are at $T_a = 25$ °C.

11. Isolation Characteristics (Unless otherwise specified, Ta = 25 °C)

| Characteristics | Symbol | Note | Test Condition | Min | Тур. | Max | Unit |
|-------------------------------------|--------|----------|-------------------------------------|----------------------|------|-----|------|
| Total capacitance (input to output) | Cs | (Note 1) | V _S = 0 V, f = 1 MHz | _ | 1.0 | _ | pF |
| Isolation resistance | Rs | (Note 1) | V _S = 500 V, R.H. ≤ 60 % | 1 × 10 ¹² | 1014 | _ | Ω |
| Isolation voltage | BVS | (Note 1) | AC, 60 s | 5000 | | | Vrms |

Note 1: This device is considered as a two-terminal device: Pins 1, 2, 3 and 4 are shorted together, and pins 5, 6, 7 and 8 are shorted together.

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C_L is approximately 15 pF which includes probe and stray wiring capacitance.



12. Characteristics Curves (Note)

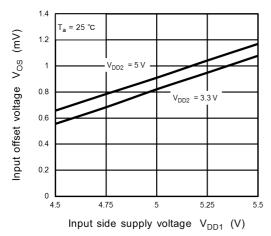


Fig. 12.1 Vos - VDD1

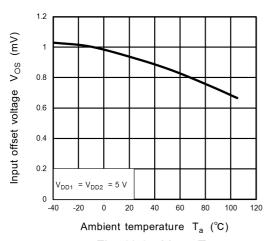


Fig. 12.3 Vos - Ta

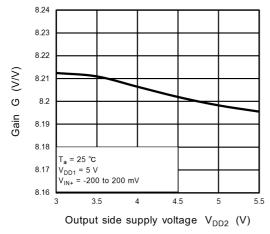


Fig. 12.5 G - V_{DD2}

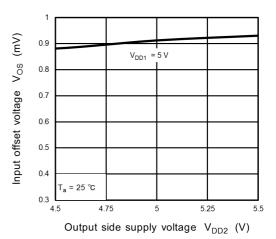


Fig. 12.2 V_{OS} - V_{DD2}

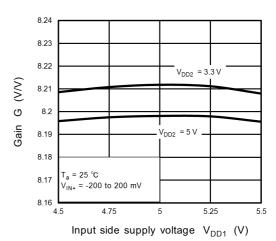


Fig. 12.4 G - V_{DD1}

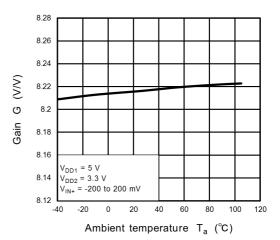
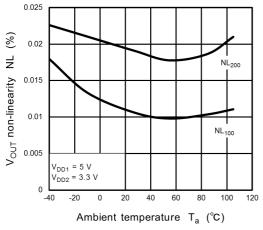
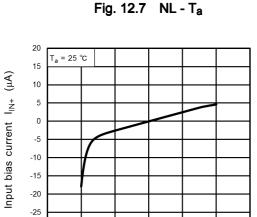


Fig. 12.6 G-Ta







Steady-state input voltages V_{IN+} (V) Fig. 12.9 I_{IN+} - V_{IN+}

-0.6

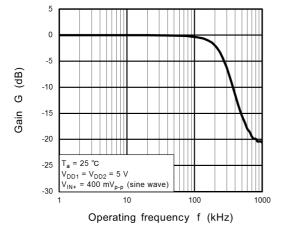


Fig. 12.11 G[dB] - f

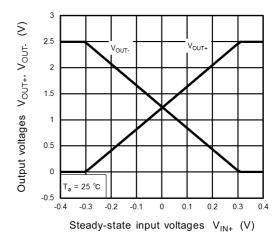


Fig. 12.8 V_{OUT} - V_{IN+}

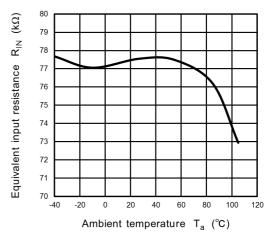


Fig. 12.10 R_{IN} - T_a

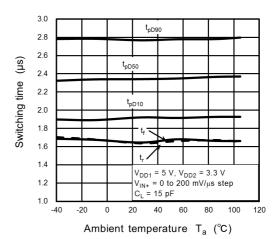


Fig. 12.12 Switching Time - Ta



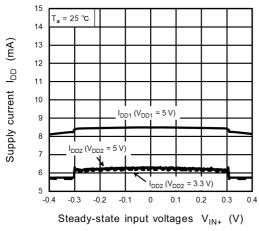


Fig. 12.13 I_{DD} - V_{IN+}

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

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13. Soldering and Storage

13.1. Precautions for Soldering

The soldering temperature should be controlled as closely as possible to the conditions shown below, irrespective of whether a soldering iron or a reflow soldering method is used.

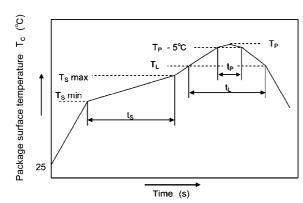
· When using soldering reflow.

The soldering temperature profile is based on the package surface temperature.

(See the figure shown below, which is based on the package surface temperature.)

Reflow soldering must be performed once or twice.

The mounting should be completed with the interval from the first to the last mountings being 2 weeks.



| | Symbol | Min | Max | Unit |
|--|----------------|-----|-----|------|
| Preheat temperature | Ts | 150 | 200 | °C |
| Preheat time | ts | 60 | 120 | S |
| Ramp-up rate (T _L to T _P) | | | 3 | °C/s |
| Liquidus temperature | TL | 217 | | °C |
| Time above T _L | t∟ | 60 | 150 | s |
| Peak temperature | T _P | | 260 | °C |
| Time during which T_c is between $(T_P - 5)$ and T_P | t _P | | 30 | s |
| Ramp-down rate (T _P to T _L) | | | 6 | °C/s |

An Example of a Temperature Profile When Lead(Pb)-Free Solder Is Used

· When using soldering flow

Preheat the device at a temperature of 150 $^{\circ}$ C (package surface temperature) for 60 to 120 seconds.

Mounting condition of 260 °C within 10 seconds is recommended.

Flow soldering must be performed once.

· When using soldering Iron

Complete soldering within 10 seconds for lead temperature not exceeding 260 $^{\circ}$ C or within 3 seconds not exceeding 350 $^{\circ}$ C

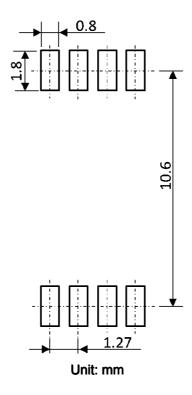
Heating by soldering iron must be done only once per lead.

13.2. Precautions for General Storage

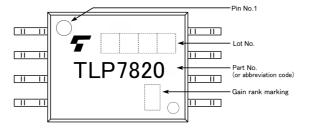
- Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5 °C to 35 °C and 45 % to 75 %, respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- · When restoring devices after removal from their packing, use anti-static containers.
- · Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.



14. Land Pattern Dimensions (for reference only)



15. Marking



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16. EN60747-5-5 Option (D4) Specification

Part number: TLP7820 (Note 1)

 The following part naming conventions are used for the devices that have been qualified according to option (D4) of EN60747.

Example: TLP7820(D4ATP4,E

D4: EN60747 option

A: Gain rank TP4: Tape type

E: [[G]]/RoHS COMPATIBLE (Note 2)

Note 1: Use TOSHIBA standard type number for safety standard application.

e.g., TLP7820(D4ATP4,E \rightarrow TLP7820

Note 2: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

| Description | Symbol | Rating | Unit |
|---|------------------|---|----------------|
| Application classification | | | |
| for rated mains voltage \leq 600 Vrms for rated mains voltage \leq 1000 Vrms | | I-IV I-III | _ |
| Climatic classification | | 40 / 105 / 21 | _ |
| Pollution degree | | 2 | _ |
| Maximum operating insulation voltage | VIORM | 1230 | Vpeak |
| Input to output test voltage, Method A V_{pr} = 1.6 × VIORM, type and sample test t_p = 10 s, partial discharge < 5 pC | Vpr | 1970 | Vpeak |
| Input to output test voltage, Method B Vpr =1.875 × VIORM, 100 % production test tp = 1 s, partial discharge < 5 pC | Vpr | 2310 | Vpeak |
| Highest permissible overvoltage (transient overvoltage, tpr = 60 s) | VTR | 8000 | Vpeak |
| Safety limiting values (max. permissible ratings in case of fault, also refer to thermal derating curve) current (input current IF, $P_{SO} = 0$) power (output or total power dissipation) temperature | lsi Pso Ts | 300 700 150 | mA mW °C |
| Insulation resistance $ \begin{array}{c} \text{VIO} = 500 \text{ V, T}_{a} = 25 \text{ °C} \\ \text{VIO} = 500 \text{ V, T}_{a} = 100 \text{ °C} \\ \text{VIO} = 500 \text{ V, T}_{a} = \text{T}_{s} \\ \end{array} $ | Rsi | ≥ 10 ¹² ≥ 10 ¹¹ ≥ 10 ⁹ | Ω |

Fig. 16.1 EN60747 Insulation Characteristics



| Minimum creepage distance | Cr | 8.0 mm |
|------------------------------|-----|--------|
| Minimum clearance | Cl | 8.0 mm |
| Minimum insulation thickness | ti | 0.4 mm |
| Comparative tracking index | СТІ | 175 |

Fig. 16.2 Insulation Related Specifications (Note)

Note: This photocoupler is suitable for **safe electrical isolation** only within the safety limit data.

Maintenance of the safety data shall be ensured by means of protective circuits.



Fig. 16.3 Marking on Packing for EN60747

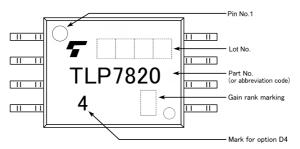
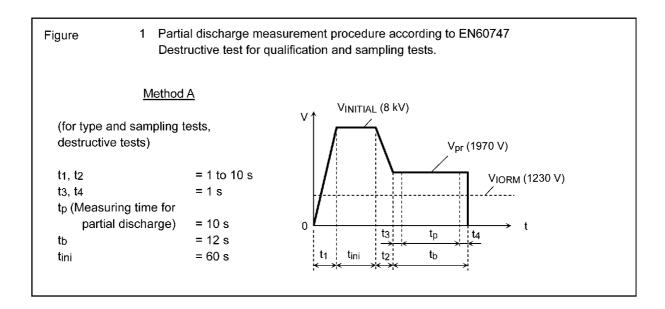
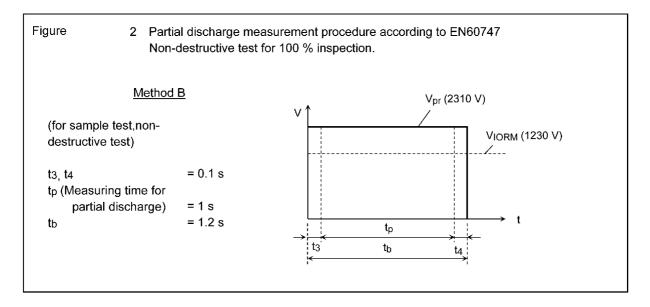


Fig. 16.4 Marking Example (Note)

Note: The above marking is applied to the photocouplers that have been qualified according to option (D4) of EN60747.







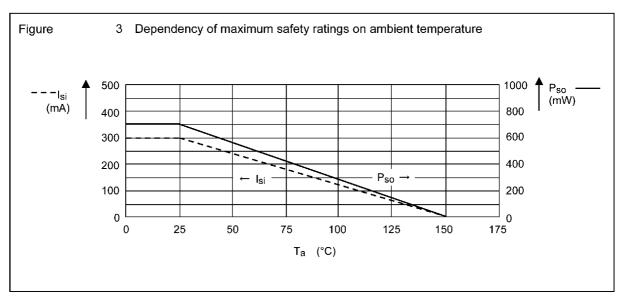


Fig. 16.5 Measurement Procedure



17. Specifications for Embossed-Tape Packing

17.1. Applicable Package

| Package Name | Product Type |
|--------------|---------------------------------|
| SO8L(LF4) | Long creepage mini flat coupler |

17.2. Product Naming Conventions

Type of package used for shipment is denoted by a symbol suffix after a part number. The method of classification is as below.

Example) TLP7820(A-TP4,E

Part number: TLP7820

Gain rank: A
Tape type: TP4

[[G]]/RoHS COMPATIBLE: E (Note 1)

Note 1: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

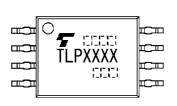
RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

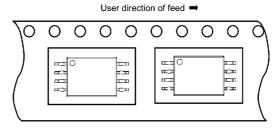
17.3. Tape Dimensions Specification

| Tape type | Quantity (pcs/reel) |
|-----------|------------------------|
| TP4 | 1500 |

17.3.1. Orientation of Device in Relation to Direction of Feed

Device orientation in the carrier cavities as shown in the following figure.





Device Orientation

17.3.2. Empty Cavities

| Characteristics | Criterion | Remarks |
|--|--------------------------|--|
| Occurrences of 2 or more successive empty cavities | 0 device | Within any given 40-mm section of tape, not including leader and trailer |
| Single empty cavity | 6 devices (max) per reel | Not including leader and trailer |

17.3.3. Tape Leader and Trailer

The start end of the tape has 50 or more empty cavities. The hub end of the tape has 50 or more empty cavities and two empty turns only for a cover tape.



17.3.4. Tape Dimensions

Tape material: Plastic (for protection against static electricity)

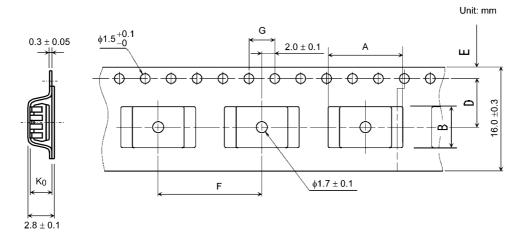


Table Tape Dimensions (unit: mm, tolerance: ±0.1)

| Symbol | Dimension | Remark |
|----------------|-----------|--|
| Α | 11.55 | _ |
| В | 6.35 | _ |
| D | 7.5 | Center line of embossed cavity and sprocket hole |
| Е | 1.75 | Distance between tape edge and sprocket hole center |
| F | 16.0 | Cumulative error +0.1/-0.3 per 10 empty cavities holes |
| G | 4.0 | Cumulative error +0.1/-0.3 per 10 sprocket holes |
| K ₀ | 2.4 | Internal space |



17.3.5. Reel Specification

Material: Plastic (for protection against static electricity)

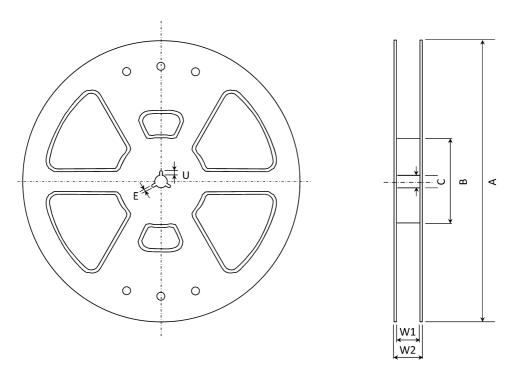
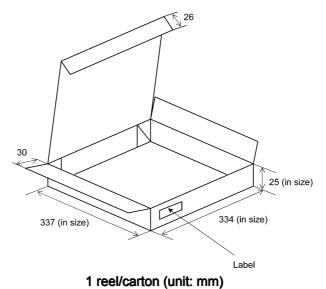


Table Reel Dimensions (unit: mm)

| Symbol | Dimension |
|--------|------------------|
| A | $\phi 330 \pm 2$ |
| В | φ100 ± 1 |
| С | ф13 ± 0.5 |
| Е | 2.0 ± 0.5 |
| U | 4.0 ± 0.5 |
| W1 | 17.4 ± 1.0 |
| W2 | 21.4 ± 1.0 |

17.4. Packing (Note)



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Note: Taping reel diameter: \$\phi330 mm



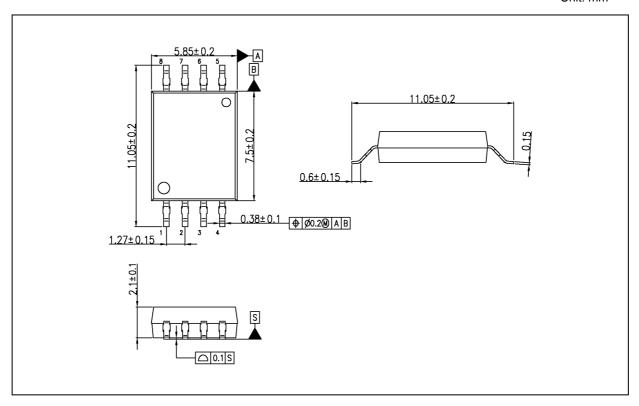
17.5. Label Format

- (1) Carton: The label provides the part number, quantity, lot number, the Toshiba logo, etc.
- (2) Reel: The label provides the part number, the taping name, quantity, lot number, etc.



Package Dimensions

Unit: mm



Weight: 0.205 g (typ.)

| | Package Name(s) |
|------------------|-----------------|
| TOSHIBA: 11-6B1A | |



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